Title (en)

ELECTRONIC CIRCUIT CHIP CONNECTION ASSEMBLY AND METHOD.

Title (de)

VERBINDUNGSZUSAMMENBAU UND VERFAHREN EINES CHIPS MIT EINEM ELEKTRONISCHEN SCHALTKREIS.

Title (fr)

ASSEMBLAGE ET PROCEDE DE CONNEXION D'UNE PUCE A CIRCUIT ELECTRONIQUE.

Publication

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Application

EP 83900116 A 19821109

Priority

US 8201584 W 19821109

Abstract (en)

[origin: WO8402051A1] The technical field of the invention concerns electronic circuit packaging and interconnecting an electronic circuit chip to a printed circuit board. Commonly, individual wires are attached to the chip pads and to the package pins manually, either by thermocompression or ultrasonic bonding. Such manual methods results in significant cost. The present invention provides a simpler and less costly assembly for and method of connecting an electronic circuit chip (30) to a printed circuit board (34). The assembly (20) includes a pressure connection frame (24) having an aperture (38) for receiving the electronic circuit chip (30), making electrical contact thereto, and also making electrical contact to electrically conductive traces (32) on the printed circuit board (34). The assembly (20) further includes a connection pressure pad (26) which contacts the pressure connection frame (24) about the aperture (38) into which is received the electronic circuit chip (30). The pressure connection frame (24), in which the electronic circuit chip (30) is received and to which the connection pressure pad (26) is secured, is inserted into a cover (22) which is then in turn secured to the printed circuit board (34) to complete the formation of the assembly (20) and the connection of the electronic circuit chip (30) to the printed circuit board (34).

IPC 1-7

H05K 7/20

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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